



IN THE UNITED STATES
PATENT AND TRADEMARK OFFICE

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6/22/01

PATENT APPLICATION

Applicant: **Vierk et al.**

Case: **A-66435/JAS/MSS**

Serial No.: **09/314,262**

Filed: **May 18, 1999**

Group Art Unit: **1773**

Examiner: **S. Resan**

Title: **HIGH MODULUS AND HIGH DAMPING PLASTIC COMPOSITE
DISC SUBSTRATE FOR IMPROVED SERVO CONTROL BY
INJECTION AND CO-INJECTION MOLDING**

ASSISTANT COMMISSIONER FOR PATENTS
Washington, D. C. 20231

S I R:

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AMENDMENT

In response to the Office Action dated February 20, 2001, please amend
the above-identified patent application as follows:

IN THE SPECIFICATION

Please amend the application by adding the following Abstract, as indicated.

A substrate for use in a data storage system is disclosed. The substrate
comprises at least one plastic composite material having a modulus of about

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